### **ABSOLUTE MAXIMUM RATINGS**

IN to GND	
BAT, SYS, EN1, EN2, POK, CHG, TMR to GND	0.3V to +6V
VL, SETI, THM to GND	0.3V to +4V
SYS to BAT	0.3V to +6V
VL to IN	16V to +0.3V
IN to BAT Current	1.0A <sub>RMS</sub>
IN to SYS Current	1.0A <sub>RMS</sub>
BAT to SYS Current	1.0A <sub>RMS</sub>
BAT Short-Circuit Duration	Continuous

Continuous Power Dissipation ( $T_A = +70$ °C)	
14-Pin 3mm x 3mm TDFN (derate 24.4mW/	°C
above +70°C)	1951.2mW
Operating Temperature Range	40°C to +85°C
Junction Temperature Range	40°C to +150°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### **ELECTRICAL CHARACTERISTICS**

 $(V_{IN}=5.0V, V_{BAT}=3.3V, \overline{EN1}=\overline{EN2}=GND, R_{SETI}=23.58k\Omega, C_{VL}=0.1\mu F, C_{SYS}=4.7\mu F, T_{A}=-40^{\circ}C$  to +85°C, unless otherwise noted. Typical values are at  $T_{A}=+25^{\circ}C$ .) (Note 1)

PARAMETER	CONDITIONS			MIN	TYP	MAX	UNITS	
IN					•			•
IN Voltage Range							14	V
IN Operating Voltage Range	(Note 2)	(Note 2)					5.50	V
IN Undervoltage Threshold	V <sub>IN</sub> rising, 500m	V hyster	esis (typ)		3.9	4.0	4.1	V
IN Overvoltage Threshold	V <sub>IN</sub> rising, 100m	V hyster	esis (typ)		5.6	5.8	6.0	V
IN Supply Current	Charging, I <sub>BAT</sub> = I <sub>SYS</sub> = 0mA			1.2	3.0	mA		
по Зарріу Сапені	Suspend, EN1 =	<u>EN2</u> = I	nigh, $I_{VL} = 0mA$			20	40	μΑ
IN to BAT Switch Leakage	V <sub>IN</sub> = 14V, BAT	- GND	TA	= +25°C		0.1	10	μA
IN to BAT Switch Leakage	VIN - 14V, DAT	- GIND	TA	= +85°C		0.5		μΑ
SYS								
SYS Regulated Voltage	$I_{SYS} = 0mA, V_{BAT} = 3.3V$			3.4	3.5	3.6	V	
	Vsys = 3.3V		$\overline{\text{EN1}} = \text{low}, \ \overline{\text{EN2}} = \text{low}$		90	95	100	mA
SYS Current Limit			$\overline{\text{EN1}} = \text{low}, \overline{\text{EN2}} = \text{high}$		450	475	500	
			$\overline{\text{EN1}} = \text{high}, \ \overline{\text{EN2}} = \text{low}$		675	712	750	
SYS Dropout Voltage ( $V_{\text{IN}}$ - $V_{\text{BAT}}$ )	I <sub>SYS</sub> = 400mA, V	'SYS = 3.	$3V, \overline{EN1} = low, \overline{E}$	EN2 = high		350	700	mV
SYS Load Regulation	$I_{SYS} = 1 \text{mA to } 6$	75mA, E	$\overline{N1}$ = high, $\overline{EN2}$ :	= low		10		mV
BAT								
BAT Regulation Voltage	I <sub>BAT</sub> = 0mA		$T_A = +25^{\circ}C$		4.18	4.20	4.22	V
BAT Negulation Voltage	IBAT = OTTA		$T_A = -40$ °C to $+85$ °C		4.16	4.20	4.24	V
Maximum Charging Current					1			А
	$\overline{\text{EN1}} = \text{low},$	Isys	SYS = 0mA		87	95	100	
	EN2 = low	Isys	sys = 50mA			45		
PAT Charging Current	$\overline{\text{EN1}} = \text{low},$	ISYS	= 0mA		450	475	500	
BAT Charging Current	EN2 = high	Isys	I <sub>SYS</sub> = 250mA			225		mA
	$\overline{\text{EN1}} = \text{high},$	Isys	= 0mA		675	712	750	
			s = 375mA			337		

## **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{IN}=5.0V, V_{BAT}=3.3V, \overline{EN1}=\overline{EN2}=GND, R_{SETI}=23.58k\Omega, C_{VL}=0.1\mu F, C_{SYS}=4.7\mu F, T_{A}=-40^{\circ}C$  to  $+85^{\circ}C$ , unless otherwise noted. Typical values are at  $T_{A}=+25^{\circ}C$ .) (Note 1)

PARAMETER	CONDITIONS			MIN	TYP	MAX	UNITS	
		$\overline{\text{EN1}} = \text{low},$	EN2 = low, Isys = 0mA	87	95	100		
BAT Prequal Current	$V_{BAT} = 2.0V$ $\overline{EN1} = low, \overline{EN2}$ 350mA		$\overline{\text{EN2}}$ = high, $I_{\text{SYS}}$ = 0 to		95		mA	
		EN1 = high 575mA	$\overline{\text{EN2}} = \text{low}, \text{Isys} = 0 \text{ to}$		95			
Soft-Start Time				1.5		ms		
BAT Prequal Threshold	V <sub>BAT</sub> rising, 150m\	/ hysteresis (†	typ)	2.9	3.0	3.1	V	
BAT Dropout Voltage (V <sub>IN</sub> - V <sub>BAT</sub> )	$V_{BAT} = 4.1V$ , $I_{BAT} = 4.1V$	= 400mA			200	400	mV	
BAT Short-Circuit Current Limit	BAT = GND			70	95	120	mA	
BAT to SYS Switch RON	V <sub>BAT</sub> = 3.5V, V <sub>SYS</sub>	= 3.4V, V <sub>IN</sub> =	= OV		50	100	mΩ	
BAT to SYS Switch Threshold	BAT rising, 160mV	hysteresis (ty	/p)	3.4	3.5	3.6	V	
Battery-Removal Threshold	BAT rising, 210mV	hysteresis (ty	/p)	4.5	4.75	5.0	V	
	V 0V		T <sub>A</sub> = +25°C		0.1	10		
	NIM = 0		T <sub>A</sub> = +85°C		0.1			
DATI Iv Over-	V <sub>INI</sub> = 2 4V		$T_A = +25^{\circ}C$		0.1	10		
BAT Leakage Current			T <sub>A</sub> = +85°C		0.1		- μA -	
	This bigh TNO bigh		T <sub>A</sub> = +25°C	-10	0.1	+10		
	$\overline{\text{EN1}} = \text{high}, \overline{\text{EN2}} =$	$T_{A} = +85^{\circ}C$			0.1			
VL								
VL Output Voltage	$I_{VL} = 0$ to $500\mu A$	3.1	3.3	3.5	V			
VL Shutdown Voltage	$V_{\overline{EN1}} = V_{\overline{EN2}} = 5V$				0		V	
ТНМ								
THM Internal Pullup Resistance					10		kΩ	
THM Resistance Threshold, Hot	10% hysteresis			3.72	3.93	4.13	kΩ	
THM Resistance Threshold, Cold	10% hysteresis			26.6	28.3	30.0	kΩ	
THM Resistance Threshold, Disabled	70% hysteresis			274	305	336	Ω	
SETI	1							
	$\overline{\text{EN1}} = \text{low}, \overline{\text{EN2}} = \text{low}$				0.28			
SETI Servo Voltage	$\overline{\text{EN1}} = \text{low}, \overline{\text{EN2}} =$	high			1.4		V	
	EN1 = high, EN2 =	· low			2.1			
SETI Resistance Range				17.68	23.58	35.36	kΩ	
POK								
DOK Trip Throphold (Viv. Vz.:-)	4.1V < V <sub>IN</sub> < 5.6V,		V <sub>IN</sub> rising	150	250	350	m\/	
POK Trip Threshold (V <sub>IN</sub> - V <sub>BAT</sub> )	$V_{BAT} = 4.1V$		V <sub>IN</sub> falling	5	55	125	mV	
POK Voltage, Low	I <del>POK</del> = 5mA		•		0.05	0.2	V	
POK Leakage Current, High			T <sub>A</sub> = +25°C		0.01	1		
TON Leakage Current, might	$V_{\overline{POK}} = 6V$	T <sub>A</sub> = +85°C			0.01		μΑ	

## **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{IN}=5.0V,\,V_{BAT}=3.3V,\,\overline{EN1}=\overline{EN2}=GND,\,R_{SETI}=23.58k\Omega,\,C_{VL}=0.1\mu F,\,C_{SYS}=4.7\mu F,\,T_{A}=-40^{\circ}C$  to  $+85^{\circ}C$ , unless otherwise noted. Typical values are at  $T_{A}=+25^{\circ}C$ .) (Note 1)

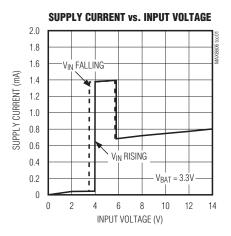
PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	
CHG						
Full-Battery Detection Current Threshold	I <sub>BAT</sub> falling	I <sub>BAT</sub> falling				
CHG Voltage, Low	ICHG = 5mA			0.05	0.02	V
CHG Leakage Current, High	Vaus - 6V	$T_A = +25^{\circ}C$		0.01	1	
Chd Leakage Current, High	$V_{CHG} = 6V$	$T_A = +85^{\circ}C$		0.01		μΑ
EN1, EN2, TMR						
Logic Input Leakage Current	$V_{\overline{TMR}} = V_{\overline{EN1}} = V_{\overline{EN2}} = 0 \text{ to } 5.5V$ $T_A = +25^{\circ}C$ $T_A = +85^{\circ}C$	$T_A = +25^{\circ}C$		0.01	1	
Logic Input Leakage Current			0.01		μΑ	
Logic Input Low Voltage					0.4	V
Logic Input High Voltage			1.6			V
THERMAL LIMIT						
Thermal-Regulation Threshold				+100		°C
Thermal-Regulation Gain	T <sub>J</sub> to I <sub>BAT</sub> , T <sub>J</sub> > +100°C			-50		mA/°C
TIMER						
Oscillator Accuracy			112	140	168	kHz
Overvoltage Turn-On Delay				800		ms
Prequal Fault Timer			24	30	36	min
Fast-Charge Fault Timer				480		min
Top-Off Timer				30		min
CHG Blinking Rate	In fault state, 50% duty		1.68	2.10	2.52	Hz

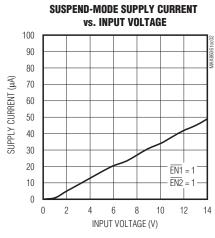
**Note 1:** Specifications are 100% production tested at T<sub>A</sub> = +25°C. Limits over the operating temperature range are guaranteed by design and characterization.

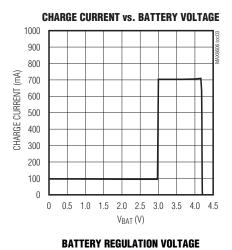
Note 2: Guaranteed by undervoltage and overvoltage threshold testing.

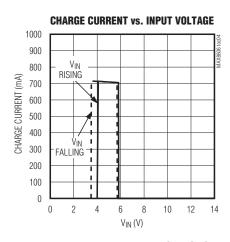
# **Typical Operating Characteristics**

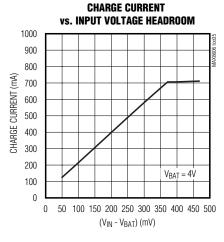
(VIN = +5V, VBAT = 3.6V, ISYS = 0, EN1 = 1, EN2 = 0, circuit of Figure 3, TA = +25°C, unless otherwise noted.)

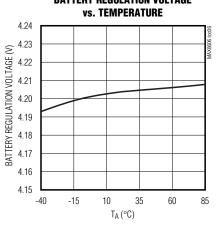


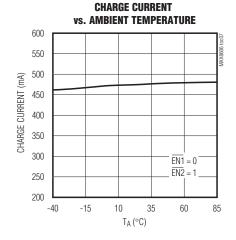


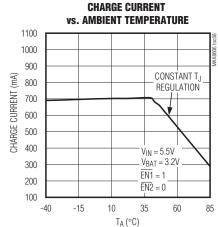












## **Pin Description**

PIN	NAME	FUNCTION
1, 2	BAT	Battery Connection. The IC delivers charging current and monitors battery voltage using BAT. Connect both BAT outputs together externally. During suspend mode, BAT is internally connected to SYS.
3	IN	Supply Voltage Input. Connect IN to a 4.25V to 5.5V supply. Charging is suspended if V <sub>IN</sub> exceeds 6V. Bypass IN to GND with a 4.7µF or larger ceramic capacitor.
4	VL	+3.3V Output Voltage and Logic Supply. VL is regulated to +3.3V and is capable of sourcing 500µA to provide power for external circuits. Bypass VL to GND with a 0.1µF or larger ceramic capacitor. VL is internally pulled to GND during suspend mode.
5	THM	Thermistor Input. Connect a $10k\Omega$ NTC thermistor from THM to GND in close proximity to the battery to monitor the battery temperature. The IC suspends charging when the temperature is outside the hot and cold limits. Connect THM to GND to disable the thermistor monitoring function.
6	CHG	Charging Status Output. CHG is an open-drain output that goes low when the battery is charging. CHG goes high impedance when the charge current drops below 50mA (typ) and the battery voltage is 4.2V (typ). CHG is high impedance when the IC is in suspend mode.
7	POK	Power-OK Monitor. POK is an open-drain output that pulls low when a valid charging source is detected at IN.
8	TMR	Timer-Selection Input. Drive TMR high to enable the microprocessor mode where the charge times are determined by an external device. Drive TMR low to use the internal prequal, fast-charge, and top-off timers.
9	EN2	Charge-Current Selection Input. Drive $\overline{\text{EN}}_{-}$ high or low to select the charge current or to put the MAX8606 into suspend mode (see Table 1).
10	EN1	Charge-Current Selection Input. Drive $\overline{\text{EN}}$ high or low to select the charge current or to put the MAX8606 into suspend mode (see Table 1).
11	GND	Ground. Connect directly to exposed paddle under the IC.
12	SETI	Charge-Current Programming Input. Connect a resistor from SETI to GND to set the maximum charging current. R <sub>SETI</sub> must be between $17.68k\Omega$ and $35.36k\Omega$ .
13, 14	SYS	System Supply Output. SYS delivers up to $1A_{RMS}$ to power an external system. Bypass SYS to GND with a $4.7\mu F$ or larger ceramic capacitor. SYS is connected to BAT through an internal $50m\Omega$ switch when $V_{BAT}$ exceeds $3.5V$ or when the MAX8606 is in suspend mode.
_	EP	Exposed Paddle. Connect to GND under the IC. Connect to a large ground plane to improve power dissipation.

## **Detailed Description**

The MAX8606 charger uses current, voltage, and thermal control loops to charge and protect a single Li+battery cell. It can start the system even when the battery is in deep saturation. The MAX8606 provides a SYS output that supplies the external system with a minimum 3.5V at 1A.

Two active-low enable inputs (EN1 and EN2) are supplied to set the SYS and charging current limits. During prequal and fast-charge modes, the CHG output status flag is pulled low. As the battery voltage approaches

4.2V, the charging current is reduced. When the charging current drops below 50mA and the battery voltage equals 4.2V, the CHG output goes high impedance, signaling a full battery. At any time during charging, if both EN1 and EN2 are driven high, the charger enters suspend mode, charging stops, and CHG goes high impedance.

The MAX8606 contains an internal timer to measure the prequal, fast-charge, and top-off charge time. If the battery voltage has not risen above 3V after 30 minutes or has not completed fast-charge in 8 hours, the charger goes into a fault state where the charging is

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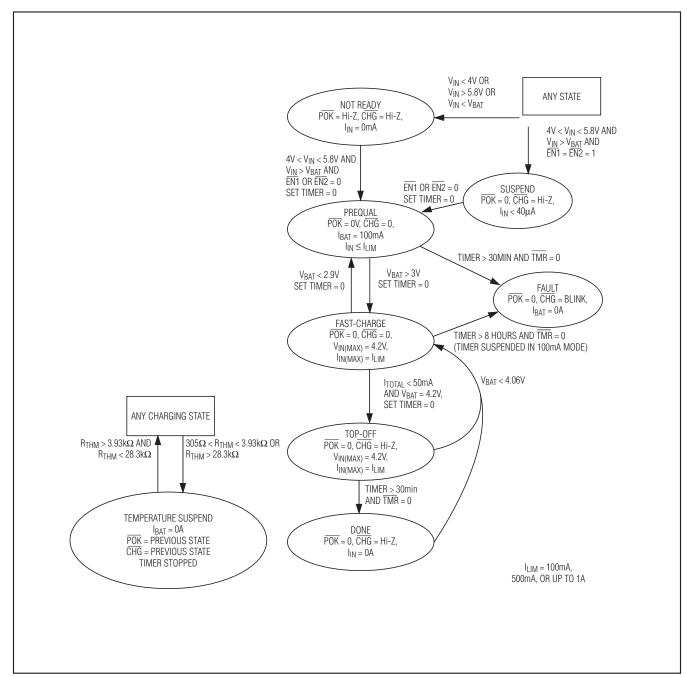


Figure 1. MAX8606 State Diagram

suspended and the CHG flag turns on and off at 2Hz. Either the input power must be cycled or the suspend mode enabled to clear the fault.

### **EN1** and **EN2** Inputs

EN1 and EN2 are logic inputs that enable the charger and select the charging current (see Table 1). Drive EN1 and EN2 high to place the IC in suspend mode.

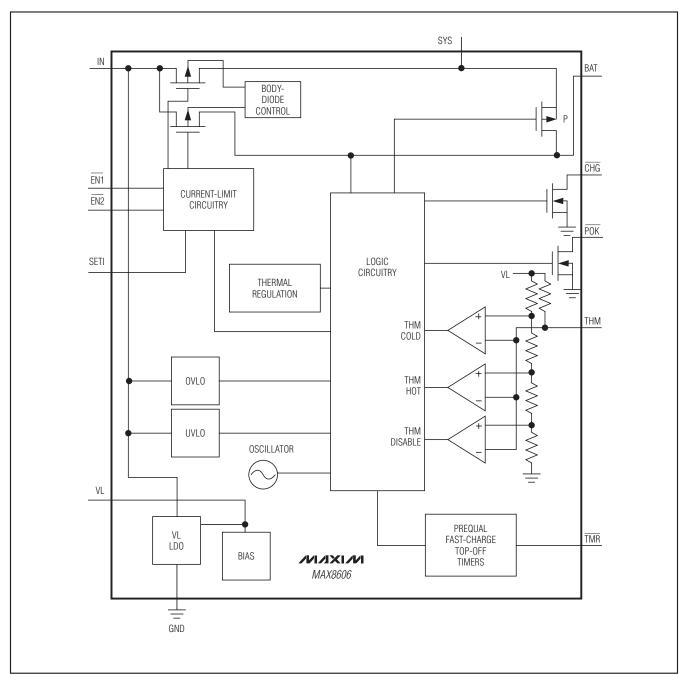


Figure 2. MAX8606 Block Diagram

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### VL Internal Voltage Regulator

The MAX8606 linear charger contains an internal linear regulator to supply the power for the IC. Bypass VL to GND with a 0.1µF ceramic capacitor. VL is regulated to 3.3V whenever the input voltage is above the battery voltage and can source up to 500µA for external loads.

### **CHG Charge-Indicator Output**

CHG is an open-drain output that indicates charger status and can be used with an LED. CHG goes low during charging. CHG goes high impedance when VBAT equals 4.2V and the charging current drops below 50mA. When the MAX8606 is used in conjunction with a microprocessor ( $\mu$ P), connect a pullup resistor between CHG and the logic I/O voltage to indicate charge status to the  $\mu$ P. CHG also indicates a timer fault. If the internal prequal or fast-charge timer expires without completing the charge cycle, charging is suspended and the CHG output "blinks" at 2.1Hz.

#### Soft-Start

To prevent input transients, the rate of change of the charge current is limited when the charger is turned on or changes its current compliance. It takes approximately 1ms for the charger to go from 0mA to the maximum fast-charge current.

### TMR Input

The MAX8606 includes a 30-minute prequalification fault timer, an 8-hour fast-charge fault timer, and a 30-minute top-off timer to terminate the changing cycle. Drive TMR low to enable the internal timers. Drive TMR high to disable the internal timers and allow an external device to determine charge times.

### **THM Input**

The MAX8606 monitors the battery temperature with an external NTC thermistor that is in close thermal contact with the battery. Select a thermistor resistance that is  $10 k\Omega$  at +25°C and has a beta of 3500 Kelvins. The IC compares the resistance from THM to GND and suspends charging when it is greater than  $28.3 k\Omega$  or less than  $3.93 k\Omega$ , which translates to a battery temperature of 0°C or +50°C, respectively. Connect THM to GND to disable the temperature control function.

#### **SYS Output**

The MAX8606 contains a SYS output that delivers up to 1ARMS at 3.5V to 4.2V to power an external system. Bypass SYS to GND with a 4.7µF or larger ceramic capacitor. When VBAT exceeds 3.5V or when the MAX8606 is in suspend mode, the MAX8606 internally connects SYS to BAT through a  $50m\Omega$  switch. When charging a battery, the load on SYS is serviced first and

Table 1. EN1 and EN2 Control

EN1	EN2	MODE
0	0	100mA
0	1	500mA
1	0	8000 x 2.1V / R <sub>SETI</sub>
1	1	Suspend

the remaining available current goes to charge the battery. SYS is connected to BAT when  $V_{\text{IN}}$  is not valid.

### DOK

The MAX8606 contains an open-drain POK output that goes low when a valid input source is detected at IN. A valid input source is one whose voltage is between 4V and 5.8V and exceeds the battery voltage by 250mV. After a valid input has been established, charging is sustained with inputs as low as 3.5V as long as the input voltage remains above the battery voltage by at least 55mV. POK is high impedance otherwise.

## \_Applications Information

### **Charge-Current Selection**

For USB applications, the charging current is internally limited to 100mA or 500mA. For wall-cube applications requiring a different current requirement, set the charging current with an external resistor from SETI to GND (RSETI). Calculate RSETI as follows:

$$RSETI = 8000 \times 2.1 \text{V} / (IBAT + ISYS)$$

where  $\overline{EN1}$  = high and  $\overline{EN2}$  = low.

The SETI input also enables the user to monitor the charging current. Under fast-charge operation, the SETI voltage regulates to 1.4V (EN1 low and EN2 high) or 2.1V (EN1 high and EN2 low). As the charging current decreases, VSETI decreases. This is due to either the thermal regulation control or voltage regulation control (4.2V) of the MAX8606. VSETI is calculated using the following equation:

VSETI = (IBAT + ISYS) x RSETI / 8000

#### Thermal Regulation

The MAX8606 features a thermal limit that reduces the charge current when the die temperature exceeds +100°C. As the temperature increases, the IC lowers the charge current by 50mA/°C above +100°C.

### **Capacitor Selection**

Connect a ceramic capacitor from SYS to GND as close to the IC as possible for proper stability. Use a 4.7µF X5R ceramic capacitor for most applications.

Connect a  $4.7\mu F$  ceramic capacitor from IN to GND as close to the IC as possible. Use a larger input bypass capacitor to reduce supply noise.

### **Thermal Considerations**

The MAX8606 is available in a thermally enhanced TDFN package with exposed paddle. Connect the exposed paddle to a large copper ground plane to provide a good thermal contact between the device and the circuit board. The exposed paddle transfers heat away from the device, allowing the MAX8606 to charge the battery with maximum current while minimizing the increase in die temperature.

### **DC Input Sources**

The MAX8606 operates from well-regulated DC sources. The full-charging input voltage range is 4.25V to 5.8V. The device survives input voltages up to 14V without damage to the IC. If V<sub>IN</sub> is greater than 5.8V (typ), the IC stops charging. An appropriate power supply must provide at least 4.25V when sourcing the desired peak charging current. It also must stay below 5.8V when unloaded.

## **Application Circuits**

#### Stand-Alone Li+ Charger

The MAX8606 provides a complete Li+ charging solution. Figure 3 shows the MAX8606 as a stand-alone Li+ battery charger. The 23.58k $\Omega$  resistor connected to SETI sets a charging current of 712mA (typ). The LED indicates when either prequal or fast-charging has begun. When the battery is charged the LED turns off.

### USB Application with AC Adapter

The MAX8606 can be configured for USB applications with an optional AC-adapter input (Figure 4). The p-channel MOSFET disconnects the USB port when the AC adapter is installed. Alternately, the USB port and AC adapter may be excluded from each other by mechanical means, such as using a single connector.

### **USB-Powered Li+ Charger**

The universal serial bus (USB) provides a high-speed serial communication port, as well as power for the remote device. The MAX8606 can be configured to charge a battery at the highest current possible from the host port. Figure 5 shows the MAX8606 as a USB battery charger. To make the circuit compatible with either 100mA or 500mA USB ports, the system software begins at 100mA charging current. The microprocessor then enumerates with the host to determine its current capability. If the host port is capable, the charging current is increased to 475mA to avoid exceeding the 500mA USB specification.

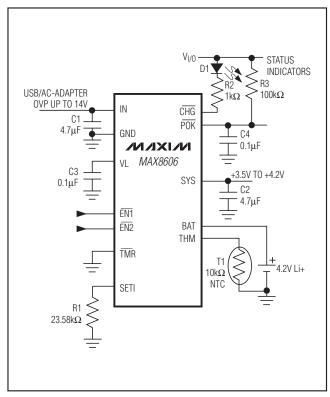


Figure 3. Stand-Alone Application

### **Layout and Bypassing**

Place the input capacitor as close to the device as possible. Provide a large copper ground plane to allow the exposed paddle to sink heat away from the device. Connect the battery to BAT as close to the device as possible to provide accurate battery voltage sensing. Make all high-current traces short and wide to minimize voltage drops. A sample layout is available in the MAX8606 evaluation kit to help speed designs.

## Chip Information

PROCESS: BICMOS

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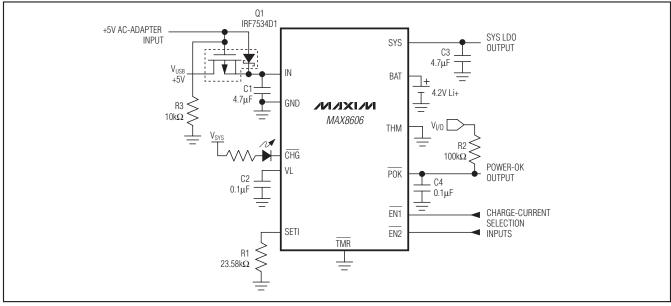


Figure 4. USB Application with AC Adapter

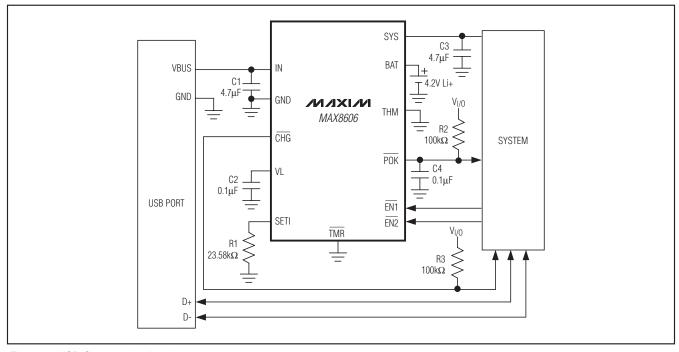
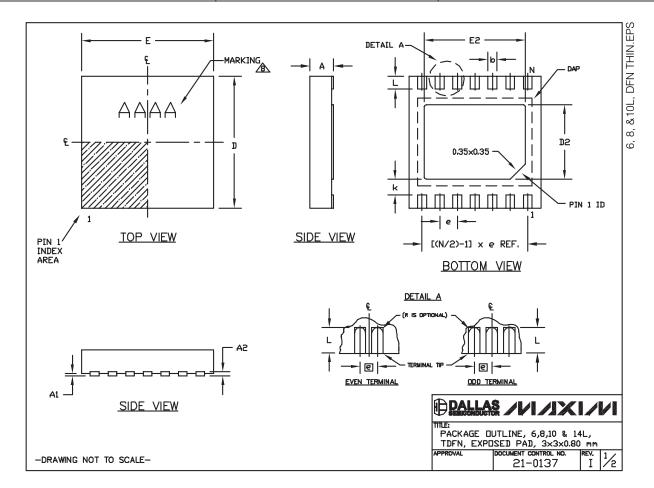


Figure 5. USB Charger Application

## **Package Information**

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages.

PACKAGE TYPE	PACKAGE CODE	DOCUMENT NO.
14 TDFN	T2444-4	<u>21-0137</u>



\_ /N/XI/N

# **Package Information (continued)**

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages.

COMMON DIMENSIONS							
SYMBOL	MIN.	MAX.					
Α	0.70	0.80					
D	2.90	3.10					
Е	2.90	3.10					
A1	0.00	0.05					
L	0.20	0.40					
k	0.25 MIN. 0.20 REF.						
A2							

PACKAGE VARIATIONS								
PKG. CODE	N	D2	E2	е	JEDEC SPEC	b	[(N/2)-1] x e	
T633-2	6	1.50±0.10	2.30±0.10	0.95 BSC	MO229 / WEEA	0.40±0.05	1.90 REF	
T833-2	8	1.50±0.10	2.30±0.10	0.65 BSC	MO229 / WEEC	0.30±0.05	1.95 REF	
T833-3	8	1.50±0.10	2.30±0.10	0.65 BSC	MO229 / WEEC	0.30±0.05	1.95 REF	
T1033-1	10	1.50±0.10	2.30±0.10	0.50 BSC	MO229 / WEED-3	0.25±0.05	2.00 REF	
T1033-2	10	1.50±0.10	2.30±0.10	0.50 BSC	MO229 / WEED-3	0.25±0.05	2.00 REF	
T1433-1	14	1.70±0.10	2.30±0.10	0.40 BSC		0.20±0.05	2.40 REF	
T1433-2	14	1.70±0.10	2.30±0.10	0.40 BSC		0.20±0.05	2.40 REF	

#### NOTES:

-DRAWING NOT TO SCALE-

- 1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
- 2. COPLANARITY SHALL NOT EXCEED 0.08 mm.
- 3. WARPAGE SHALL NOT EXCEED 0.10 mm.
- 4. PACKAGE LENGTH/PACKAGE WIDTH ARE CONSIDERED AS SPECIAL CHARACTERISTIC(S).
- 5. DRAWING CONFORMS TO JEDEC MO229, EXCEPT DIMENSIONS "D2" AND "E2", AND T1433-1 & T1433-2.
- 6. "N" IS THE TOTAL NUMBER OF LEADS.
- 7. NUMBER OF LEADS SHOWN ARE FOR REFERENCE ONLY.
- MARKING IS FOR PACKAGE ORIENTATION REFERENCE ONLY.



TTLE:

PACKAGE DUTLINE, 6,8,10 & 14L,
TDFN, EXPOSED PAD, 3×3×0.80 mm
PPROVAL | DOCUMENT CONTROL NO. | Rev.

DOCUMENT CONTROL N 21-0137 I 2/2

**Revision History** 

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	8/05	Initial release	_
1	12/08	Updated Continuous Power Dissipation and derating factor in <i>Absolute Maximum Ratings</i>	2

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